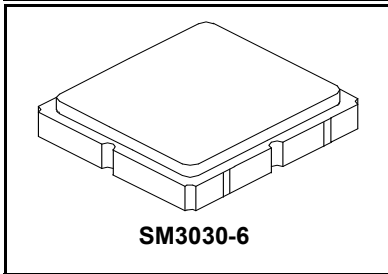


**SF2124E**

**2441.8 MHz  
SAW Filter**



- **Designed for RF Front-end Applications**
- **Low Insertion Loss**
- **3.0 x 3.0 x 1.3 mm Surface-mount Case**
- **No Matching Circuit Required**

**Absolute Maximum Ratings**

Rating	Value	Units
Input Power Level	+20	dBm
DC Voltage on any Non-ground Terminal	0	Volts
Operable Temperature Range	-45 to +125	°C
Specification Temperature Range	-40 to +100	°C
Storage Temperature Range in Tape and Reel	-40 to +85	°C
Maximum Soldering Profile - 5 cycles, 10 Seconds Max	260	°C

**Electrical Characteristics**

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	$f_C$	1		2441.8		MHz
Insertion Loss, 2400.0 to 2483.5 MHz	IL	at 100°C		2.1	4.0	dB
		at 85°C		2.1	3.2	
		at 25°C		2.1	3.1	
Amplitude Ripple, 2400.0 to 2483.5 MHz				0.9	3.0	dB <sub>P-P</sub>
Attenuation, referenced to 0 dB						dB
DC to 1700 MHz			20.0	29.0		
1700 to 2200 MHz			25.0	30.0		
2700 to 3100 MHz			30.0	40.0		
3100 to 4000 MHz			20.0	29.0		
4000 to 5000 MHz			10.0	20.0		
VSWR, 2400 to 2483.5 MHz				1.7	2.6	
Source Impedance	$Z_S$			50		$\Omega$
Load Impedance	$Z_L$			50		$\Omega$
Single-Ended Input / Output Impedance Match	No matching network required for operation at 50 ohms					
Case Style	SM3030-6 3 x 3 mm Nominal Footprint					
Lid Symbolization, Y=year, WW=week, S=shift	646 YWWS					

**Electrical Connections**

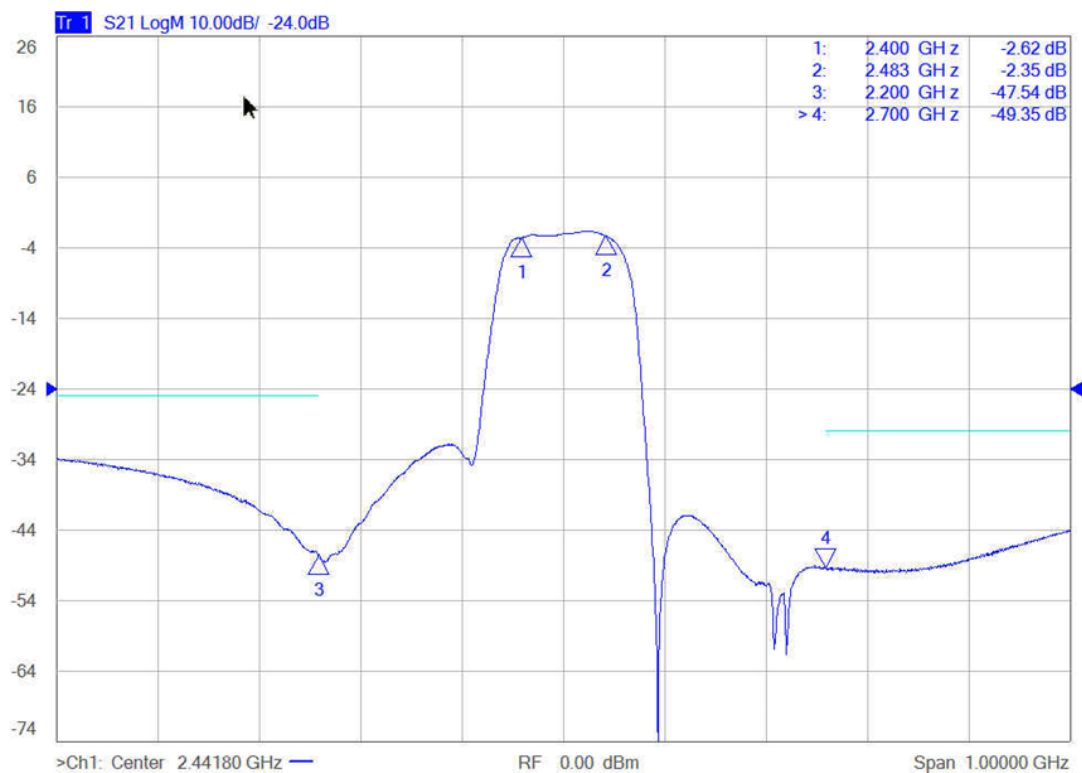
Pin #	Description	Pin #	Description
1	Ground	4	Ground
2	Input	5	Output
3	Ground	6	Ground

 **CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.**  
**NOTES:**

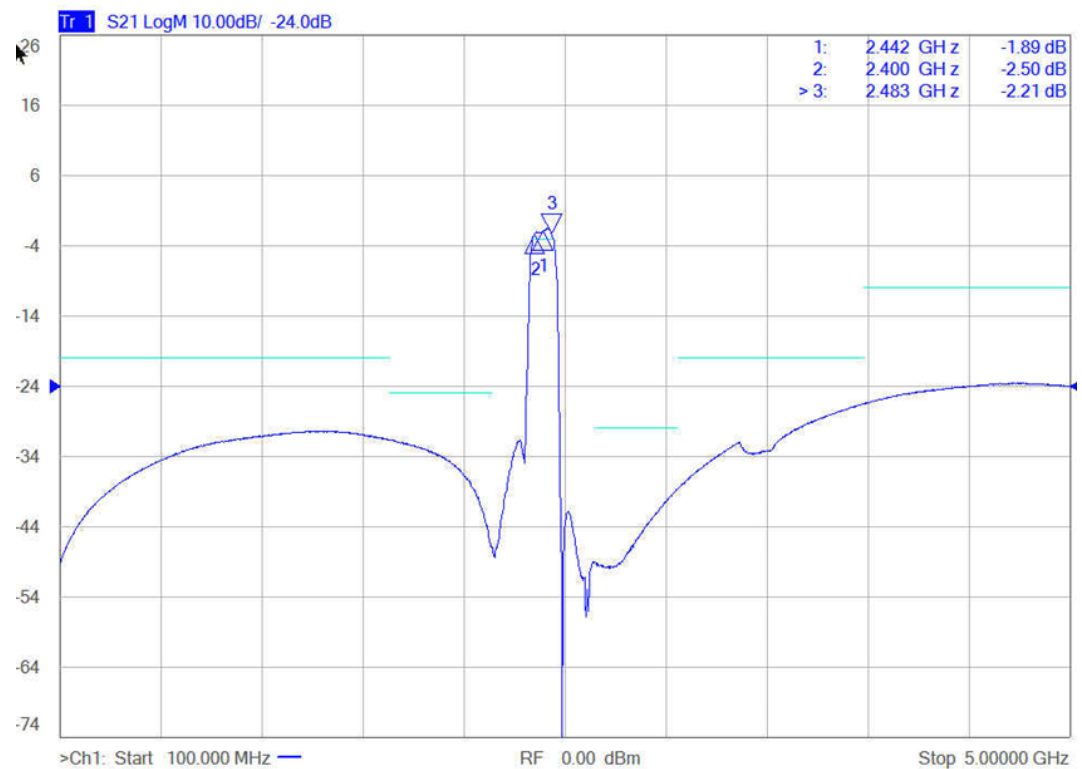
1. Unless noted otherwise, all specifications apply over the operating temperature range with filter soldered to the specified demonstration board with impedance matching to 50  $\Omega$  and measured with 50  $\Omega$  network analyzer.
2. Unless noted otherwise, all frequency specifications are referenced to the nominal center frequency,  $f_C$ .
3. Rejection is measured as attenuation below the minimum IL point in the passband. Rejection in final user application is dependent on PCB layout and external impedance matching design. See Application Note No. 42 for details.
4. "LRIP" or "L" after the part number indicates "low rate initial production" and "ENG" or "E" indicates "engineering parts."
5. The design, manufacturing process, and specifications of this filter are subject to change.
6. Either Port 1 or Port 2 may be used for either input or output in the design. However, impedances and impedance matching may vary between Port 1 and Port 2, so that the filter must always be installed in one direction per the circuit design.
7. US and international patents may apply.
8. Murata, stylized Murata logo, and Murata N.A., Inc. are registered trademarks of Murata Manufacturing Co., Ltd.

# Frequency Characteristics :

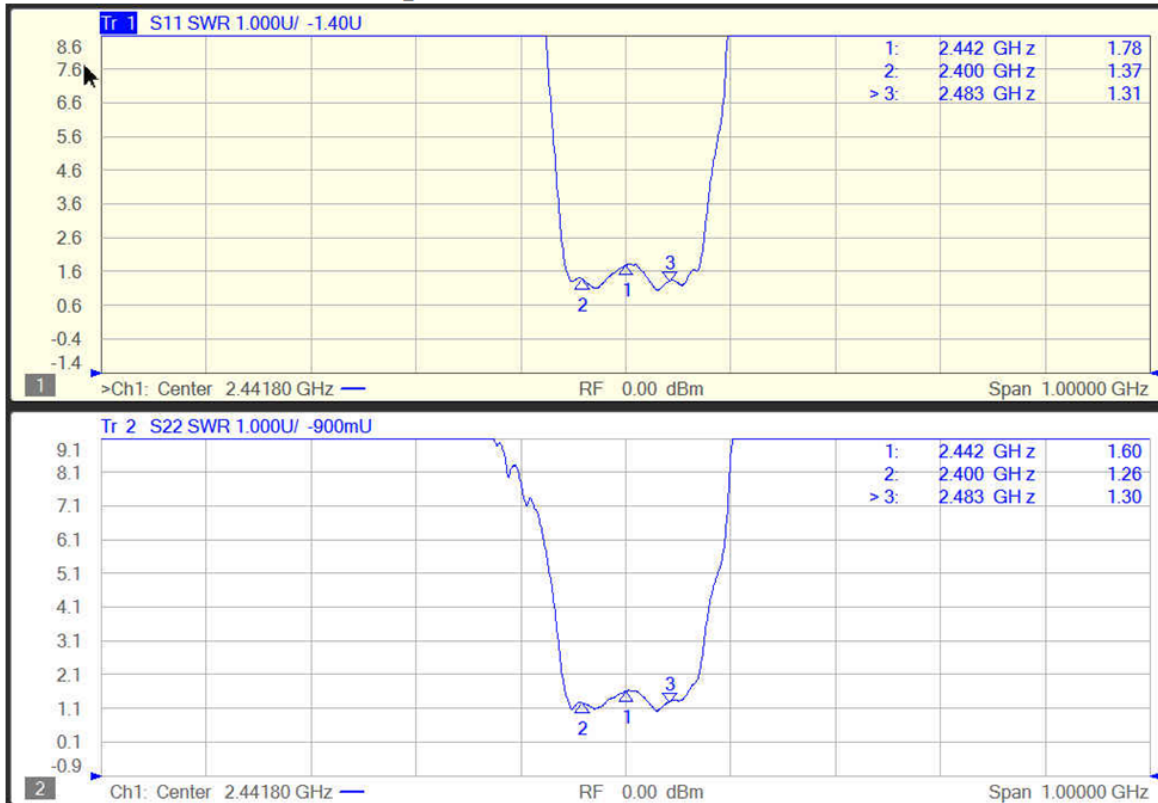
## S21 response (span: 1 GHz)



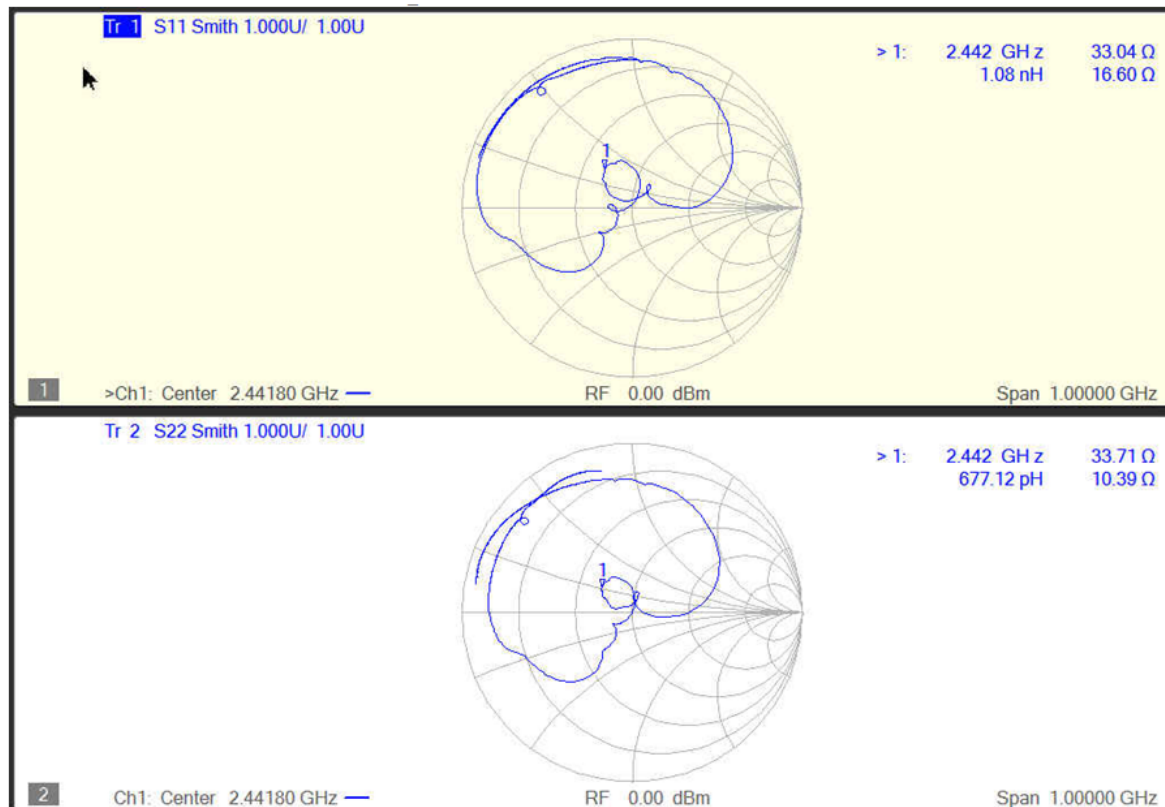
## S21 response (span: 100 MHz - 5 GHz)



## S11 and S22 SWR:

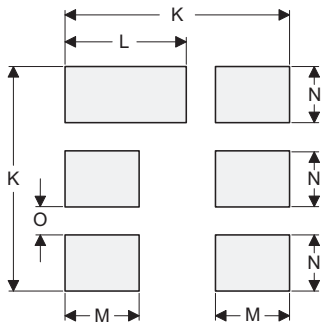
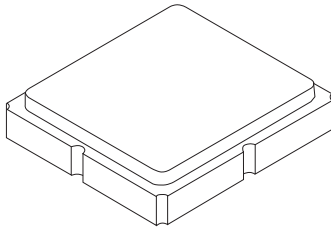


## S11 and S22 Smith Chart



# SM3030-6 Case

## 6-Terminal Ceramic Surface-Mount Case 3.0 X 3.0 mm Nominal Footprint



PCB Footprint Top View

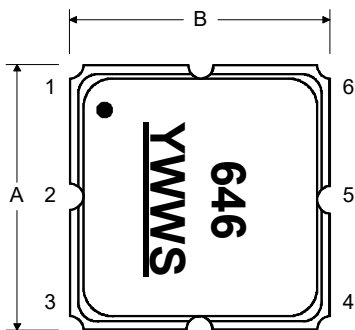
### Case and PCB Footprint Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.87	3.00	3.13	0.113	0.118	0.123
B	2.87	3.00	3.13	0.113	0.118	0.123
C	1.12	1.25	1.38	0.044	0.049	0.054
D	0.77	0.90	1.03	0.030	0.035	0.040
E	2.67	2.80	2.93	0.105	0.110	0.115
F	1.47	1.60	1.73	0.058	0.063	0.068
G	0.72	0.85	0.98	0.028	0.033	0.038
H	1.37	1.50	1.63	0.054	0.059	0.064
I	0.47	0.60	0.73	0.019	0.024	0.029
J	1.17	1.30	1.43	0.046	0.051	0.056
K		3.20			0.126	
L		1.70			0.067	
M		1.05			0.041	
N		0.81			0.032	
O		0.38			0.015	

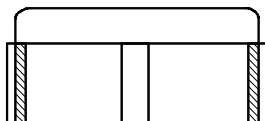
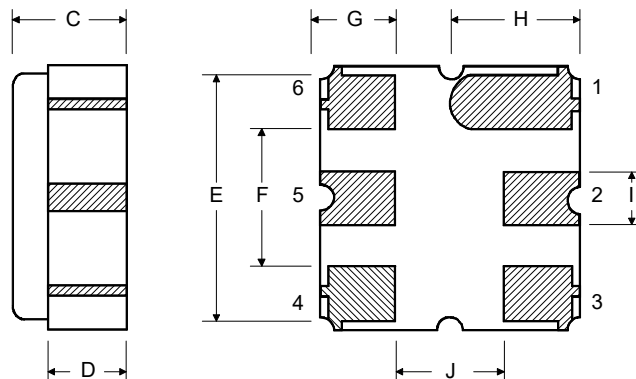
### Case Materials

Materials	
Solder Pad Plating	0.3 to 1.0 $\mu\text{m}$ Gold over 1.27 to 8.89 $\mu\text{m}$ Nickel
Lid Plating	2.0 to 3.0 $\mu\text{m}$ Nickel
Body	$\text{Al}_2\text{O}_3$ Ceramic
Pb Free	

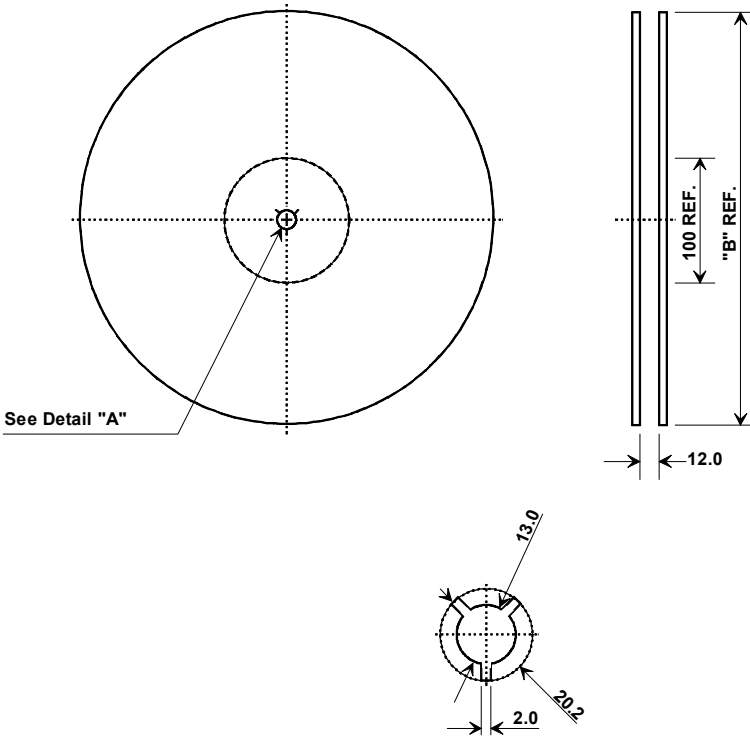
### TOP VIEW



### BOTTOM VIEW

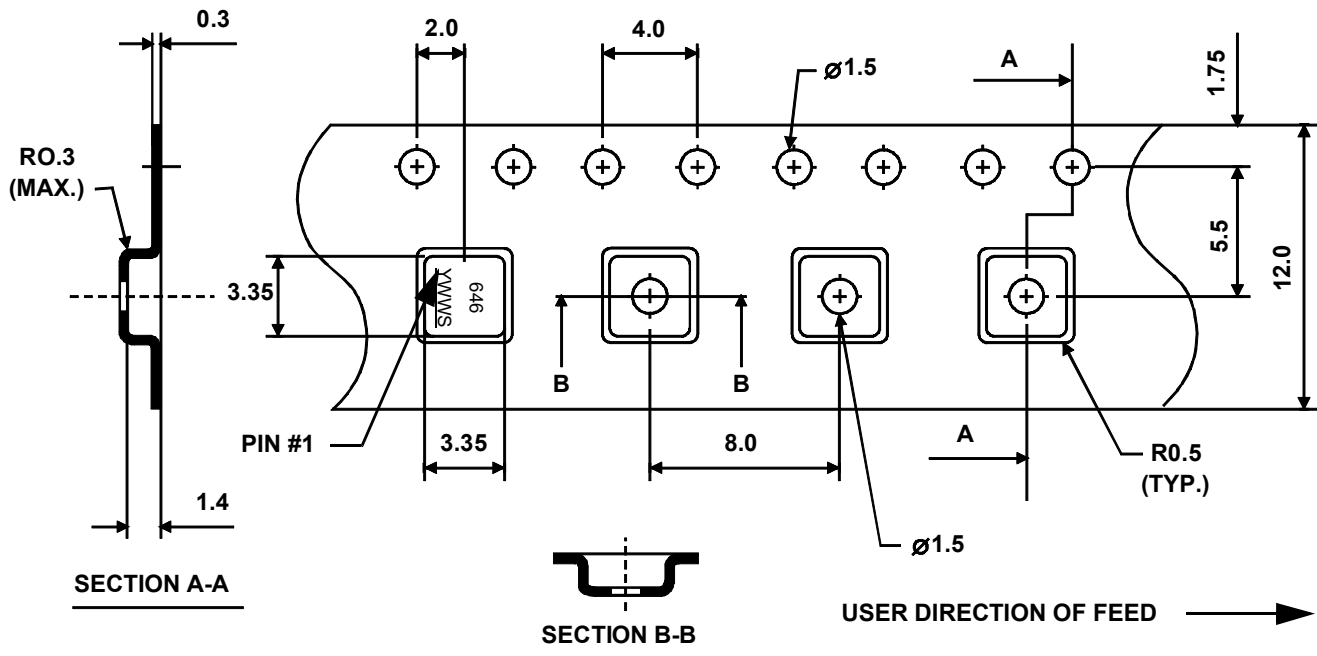


## Tape and Reel Specifications



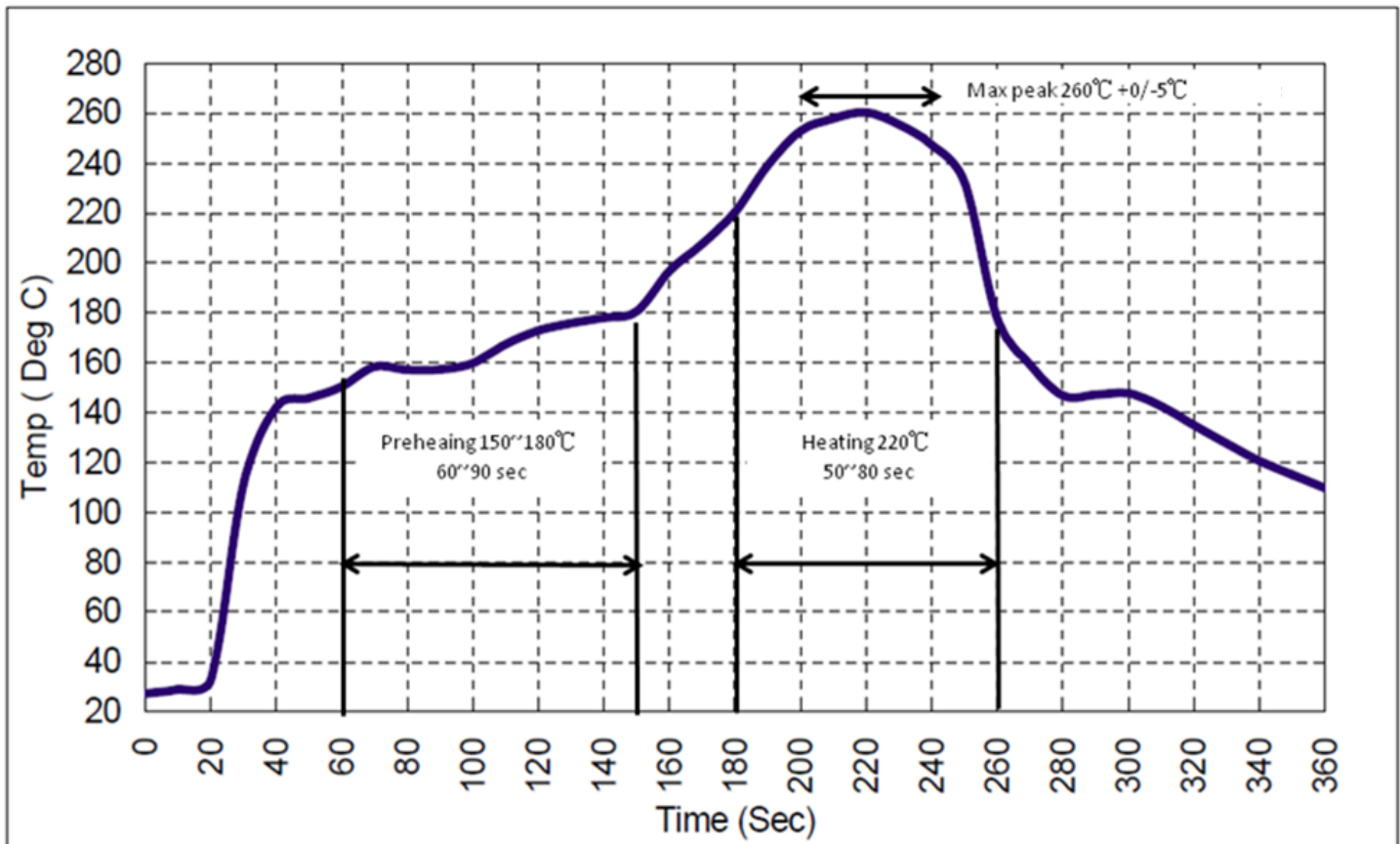
"B"		Quantity Per Reel
Inches	millimeters	
7	178	500
13	330	3000

## COMPONENT ORIENTATION



## Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C+0/-5°C peak (10 seconds).
4. Time: 5 times maximum.



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